

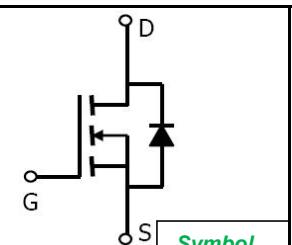
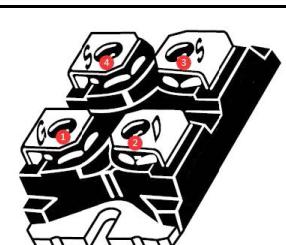
**800V N-Channel Power MOSFET****FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

**APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

**Parameters Summary****VDS:800V ID (at VGS=10V):50A Rds(on) (at VGS=10V):120mΩ(Typ.)**

		SOT-227
<b>SP50N80FX</b>		

**Device Ordering Marking Packing Information**

Ordering Number	Package	Marking	Packing
SP50N80FX	SOT-227	SP50N80FX	Tube

**Absolute Maximum Ratings T<sub>C</sub> = 25°C, unless otherwise noted**

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	800	V
Continuous Drain Current	I <sub>D</sub>	50	A
Pulsed Drain Current (note1)	I <sub>DM</sub>	200	A
Gate-Source Voltage	V <sub>GSS</sub>	±30	V
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	4500	mJ
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	60	mJ
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	690	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

*Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.*

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	0.18	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	40	

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	800	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 800\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1.0	$\mu\text{A}$
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 30\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$I_{\text{DS}} = 250\mu\text{A}$	2.5	--	4.5	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 25\text{A}$	--	120	130	$\text{m}\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	14600	--	pF
Output Capacitance	$C_{\text{oss}}$		--	1300	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	66	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 400\text{V}, I_D = 50\text{A}, V_{\text{GS}} = 10\text{V}$	--	360	--	nC
Gate-Source Charge	$Q_{\text{gs}}$		--	80	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	120	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 50\text{A}, R_G = 10\Omega$	--	110	--	ns
Turn-on Rise Time	$t_r$		--	200	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	160	--	
Turn-off Fall Time	$t_f$		--	185	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	50	A
Pulsed Diode Forward Current	$I_{\text{SM}}$		--	--	400	
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 25\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.4	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_{\text{GS}} = 0\text{V}, I_S = 50\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	520	--	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		--	5.0	--	$\mu\text{C}$

**Notes**

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

Figure 1. Maximum Transient Thermal Impedance

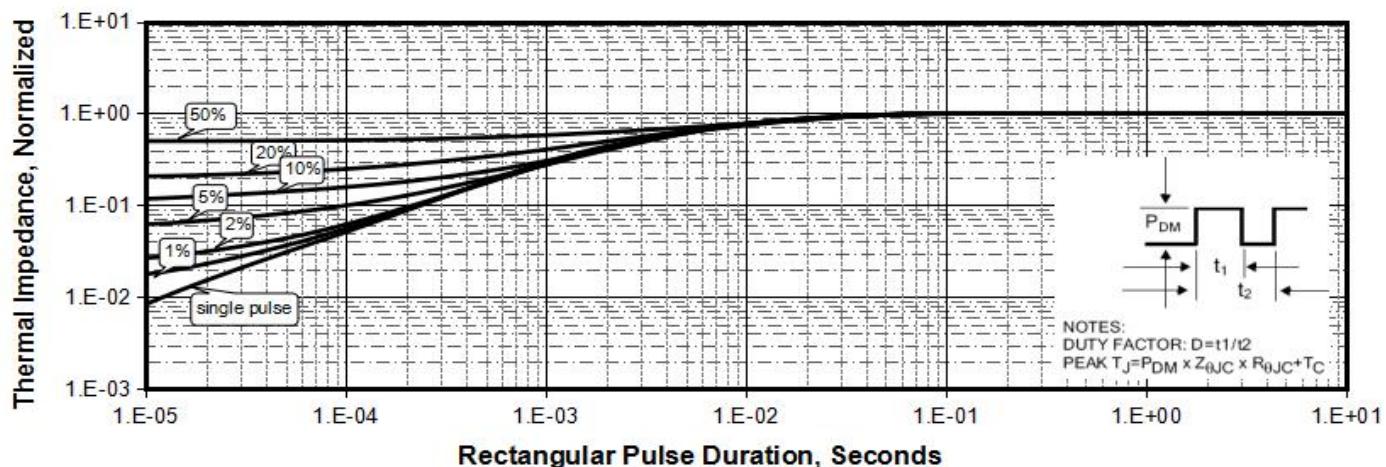


Figure 2 . Maximum Power Dissipation

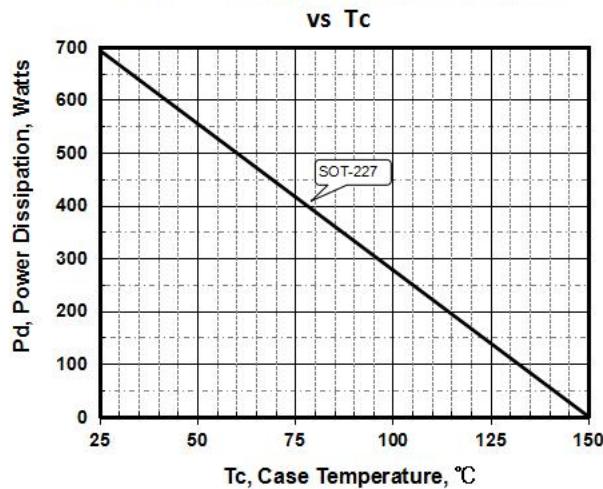


Figure 3 .Maximum Continuous Drain Current vs Tc

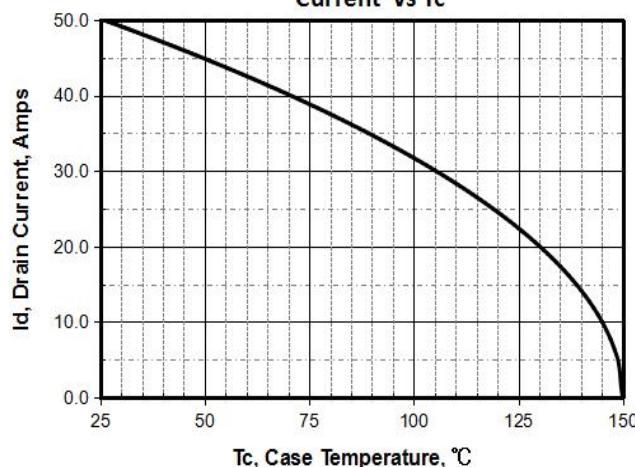


Figure 4. Output Characteristics

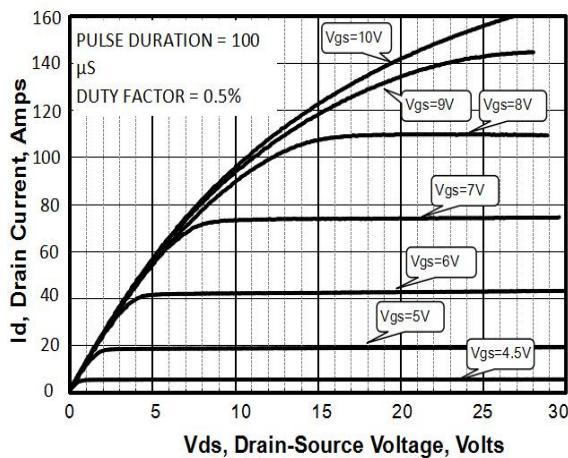
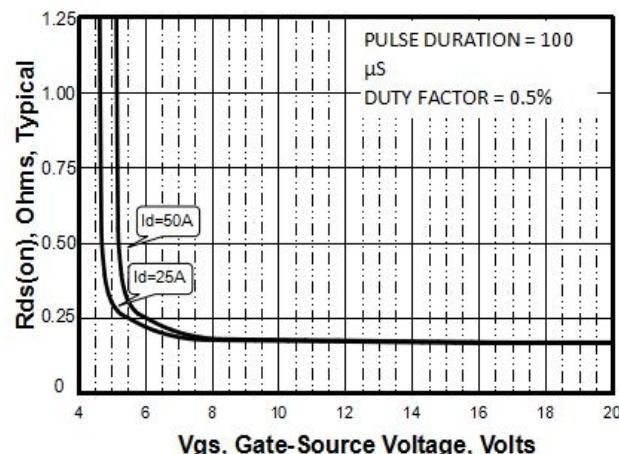
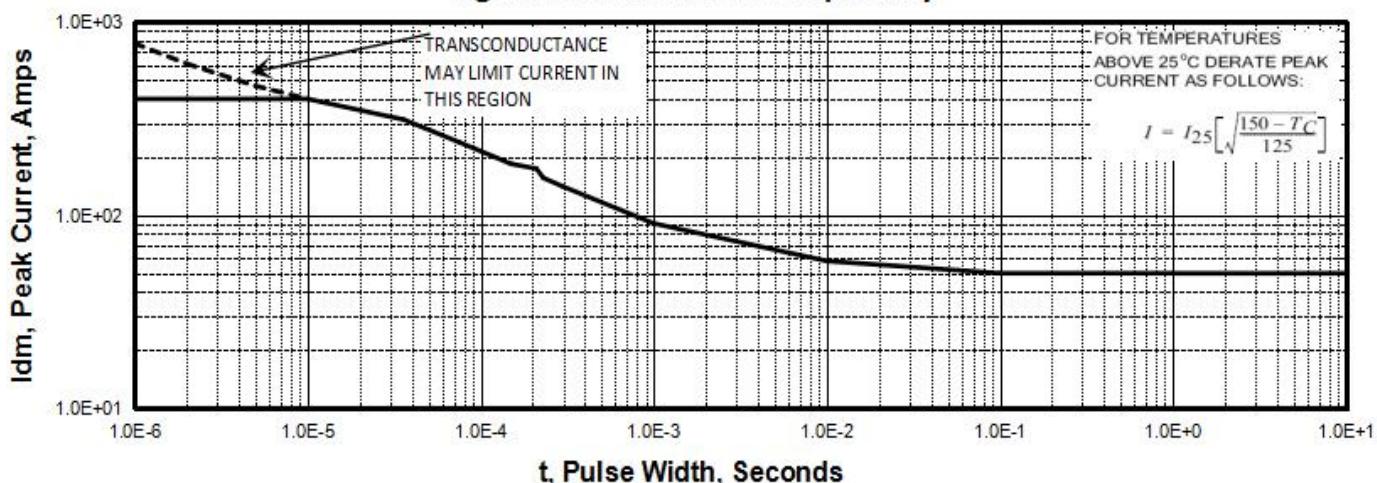
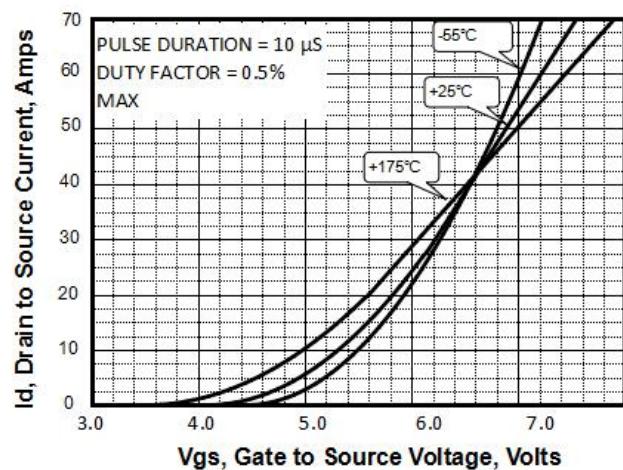
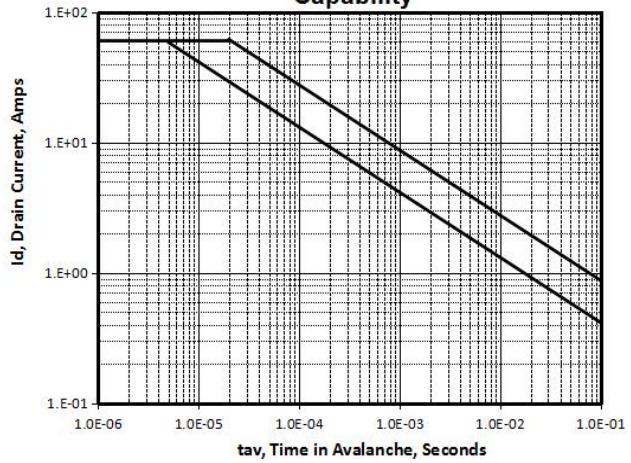
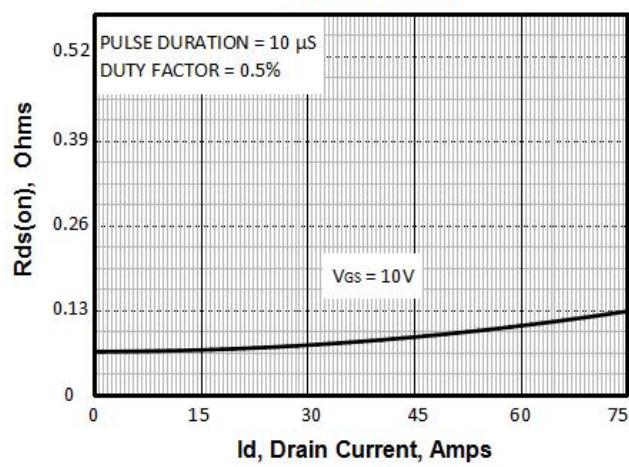
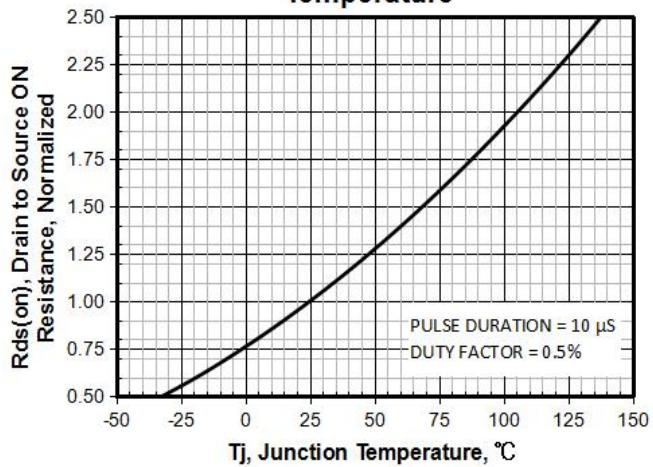
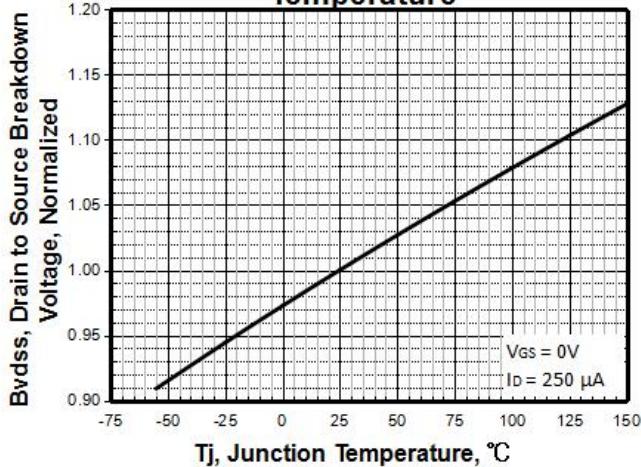


Figure 5. Rdson vs Gate Voltage

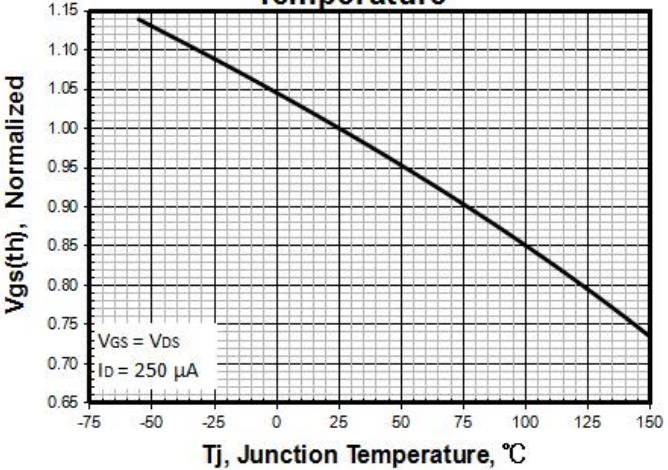


**Figure 6. Peak Current Capability****Figure 7. Transfer Characteristics****Figure 8. Unclamped Inductive Switching Capability****Figure 9. Drain to Source ON Resistance vs Drain Current****Figure 10. Rdson vs Junction Temperature**

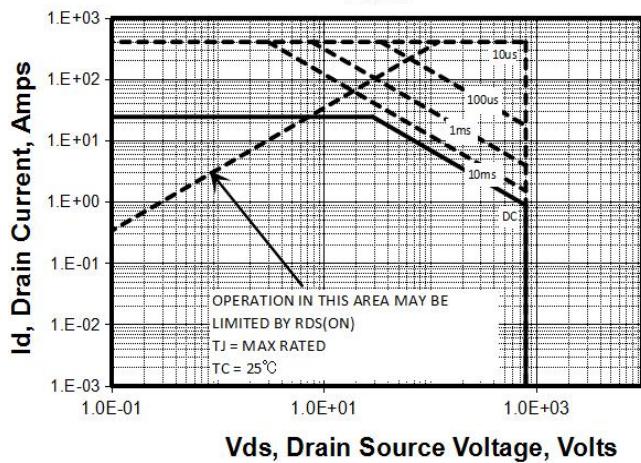
**Figure 11. Breakdown Voltage vs Temperature**



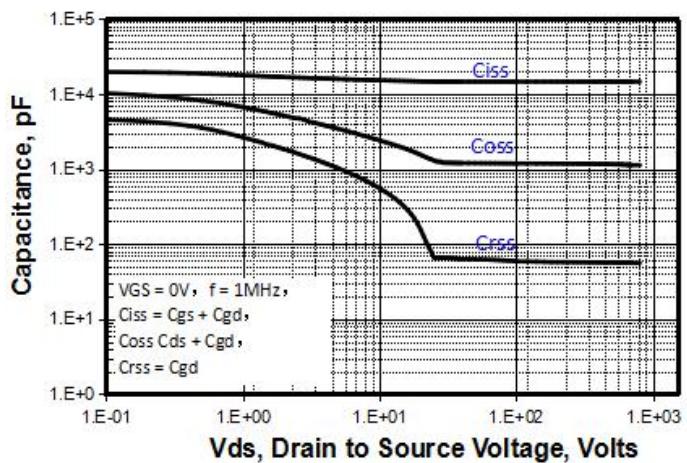
**Figure 12. Threshold Voltage vs Temperature**



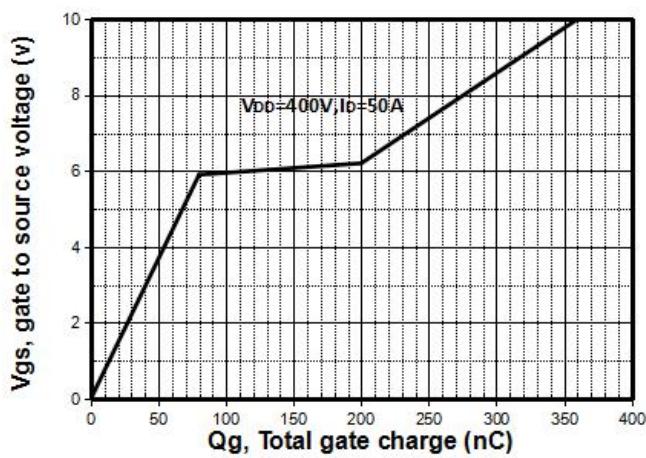
**Figure 13 . Maximum Safe Operating Area**



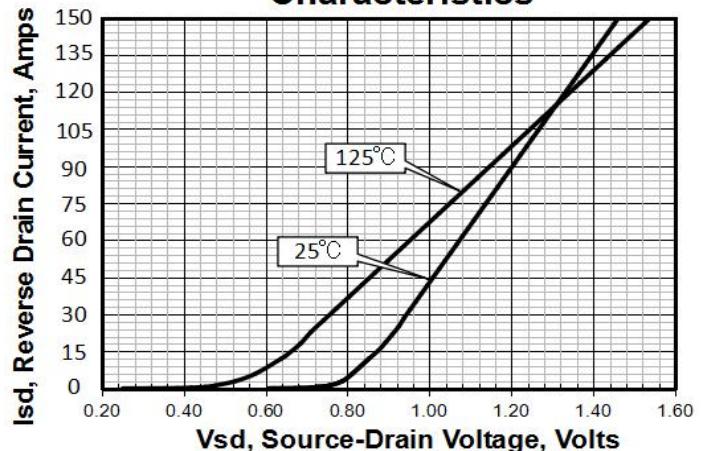
**Figure 14. Capacitance vs Vds**

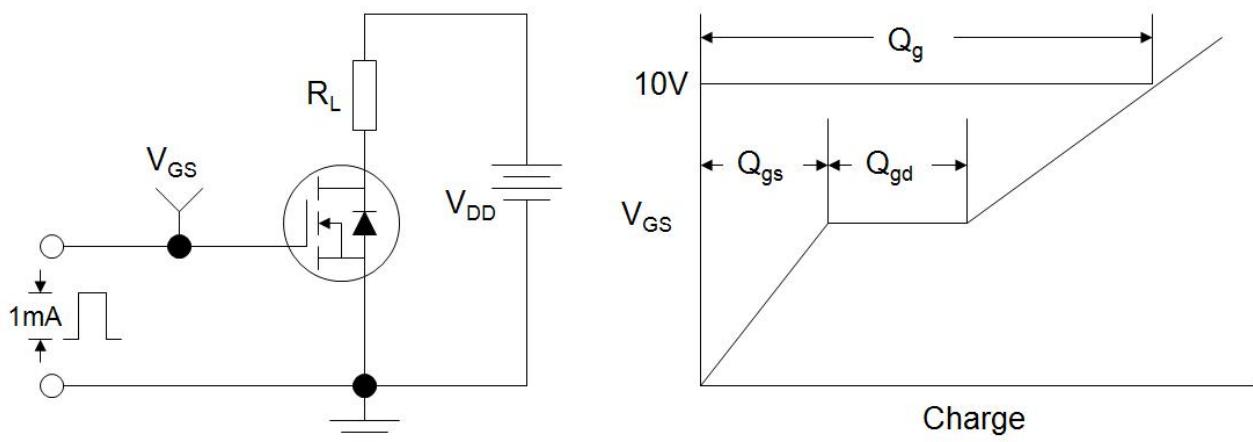
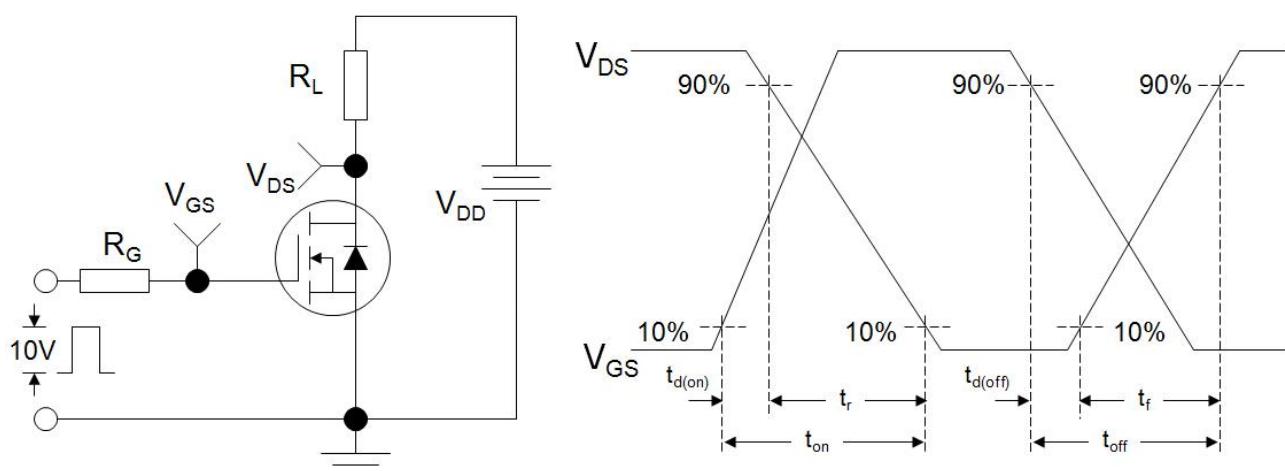


**Figure 15 .Typical Gate Charge**



**Figure 16.Body Diode Transfer Characteristics**



**TEST CIRCUITS AND WAVEFORMS****Figure A: Gate Charge Test Circuit and Waveform****Figure B: Resistive Switching Test Circuit and Waveform****Figure C: Unclamped Inductive Switching Test Circuit and Waveform**